

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "P12V\_SUPPLY" represents connection to the +12V input power.
2. The netname "P6P2V" represents connection to the +6.2V power buss.
3. The netname "V5P0VADS" represents connection to the +5.0V power buss.
4. The netname "V3P3VADS" represents connection to the +3.3V power buss
5. The netname "V2P5VREF" represents connection to the +2.5V reference buss
6. The netname "V2P5VREFBUF" represents connection to the +2.5V buffered reference buss.
7. The netname "GND" represents connection to the ground plane.
8. A "Z" suffix on a signal name indicates an active low signal.
9. All components with designators "U\*", "Q\*", and "D\*" are electrostatic discharge sensitive.
10. All resistor values are in ohms.
11. All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	09/23/2013	HPC
A	ECO 2136062: REV A Release	11/09/2013	HPC
B	ECO 2138296: REV B Release	12/05/2013	GW
C	ECO 2139940: REV C Release	02/14/2014	HPC
D	ECO 2140577: REV D Release	03/12/2014	HPC

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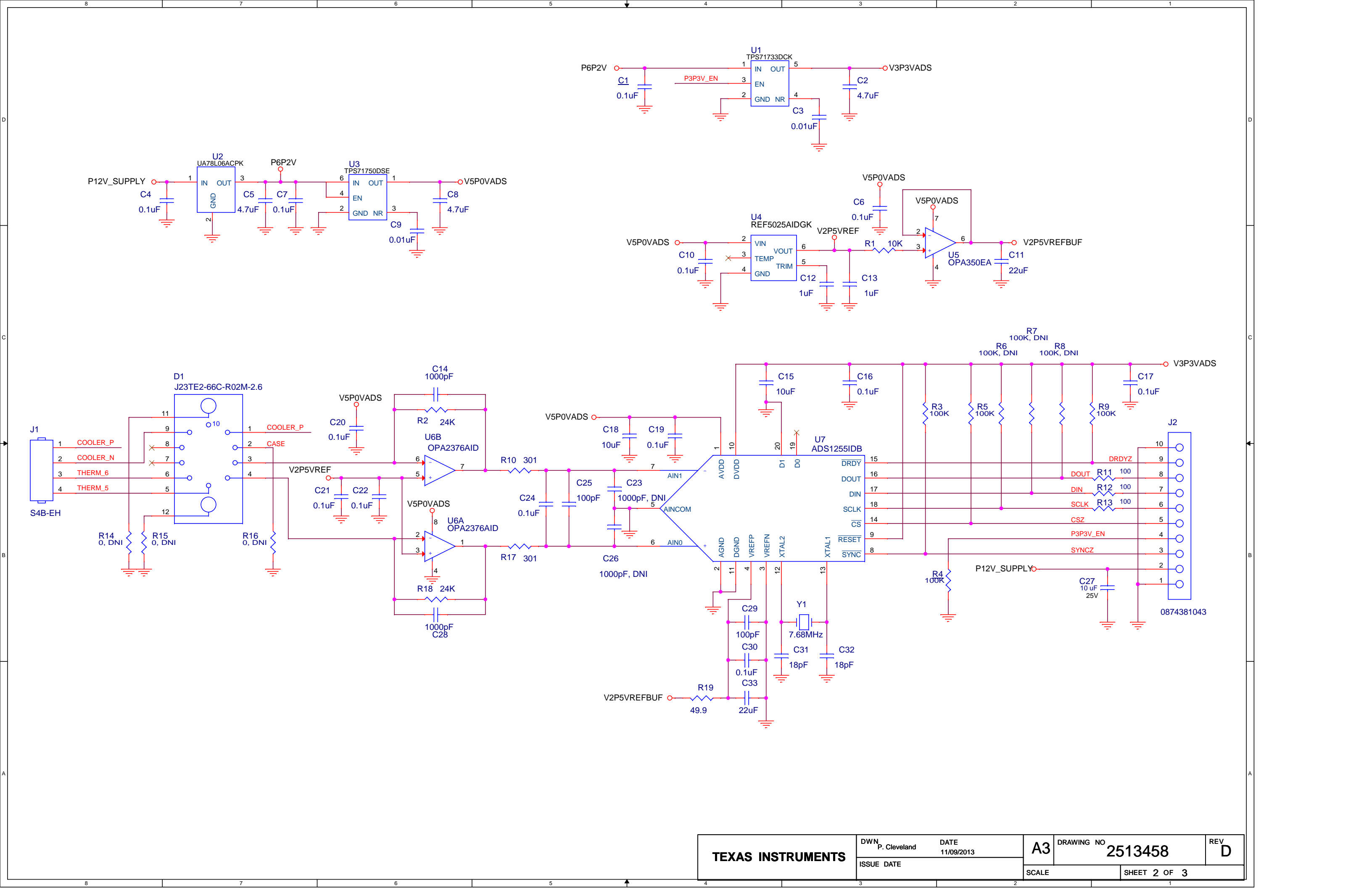
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		DWN P. Cleveland	DATE 11/09/2013	<b>TEXAS INSTRUMENTS</b>  (C) COPYRIGHT 2014 TEXAS INSTRUMENTS ALL RIGHTS RESERVED		
		ENGR Eric Pruett				
		APVD Joe Siddall				
		MFG				
	0314CP	QA		TITLE  ESD, NIRscan Detector, Amplifier, ADS		
NEXT ASSY	USED ON					
APPLICATION		SW Allegro Design Entry 16.6		A3	DRAWING NO 2513458	REV D
			SCALE		SHEET 1 of 3	



Revision History

Rev. -: Draft Release ~ 09/23/2013
Rev. A: ECO 2136062 ~ 11/09/2013
Rev. B: ECO 2138296 ~ 12/05/2013 ~ Change J2 Part Number
Rev. C: ECO 2139940 ~ 02/14/2014 ~ Up-date title block, disclaimer
Rev. D: ECO 2140577 ~ 03/12/2014 ~ Cut U7-9, U1-3; Wire J2-4 to U1-3; Cut R4 at P3P3VADS, Ground R4; Add R6, R7, R14, R15, R16, C23, & C26 to DNI list

Schematic Revision History

TEXAS INSTRUMENTS	DWN P. Cleveland	DATE 11/09/2013	A3	DRAWING NO 2513458		REV D
	ISSUE DATE			SCALE		SHEET 3 OF 3

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